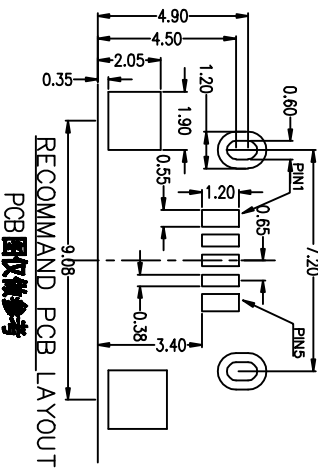
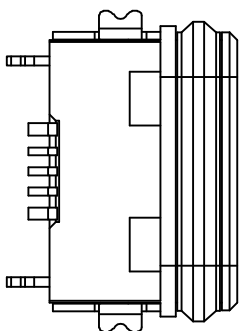
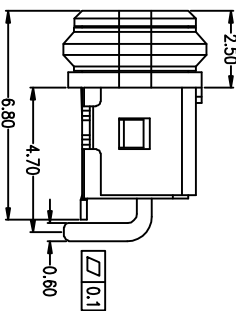
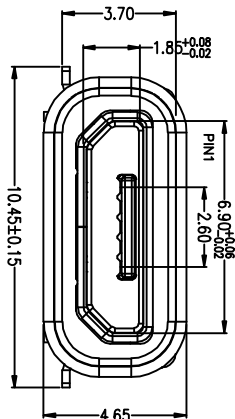
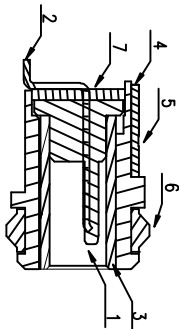
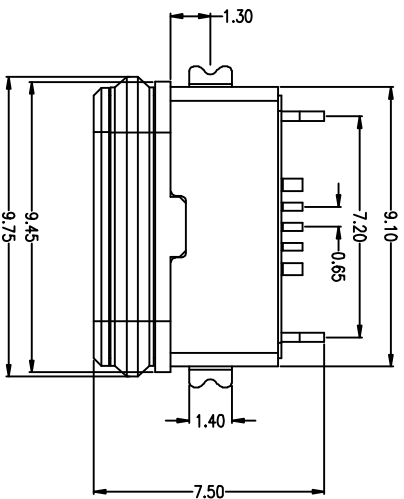
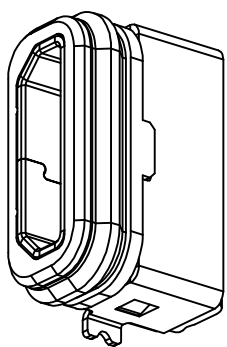


MAPX	MODIFICATION	DATE
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- Note:
- 1.Material:
- 1.1 Housing: High temperature thermoplastic
  - 1.2 Contact: copper alloy,t=0.20mm
  - 1.3 Shell: SUS304,t=0.30mm
  - 1.4 cover: High temperature thermoplastic
  - 1.5 out Shell: SUS304 T=0.25
  - 1.6 Ring: SILICON
  - 1.7 Epoxy: Epoxy
- 2.Specification:
- 2.1 Current rating:1.5PIN 2.0A Max/2.3,4PIN 1A Max.
  - 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
  - 2.3 Contact resistance: 30 mΩ Max.
  - 2.4 Insulation resistance: 100 MΩ Min.
  - 2.5 Total mating force: 3.57 Kgf Max.
  - 2.6 Total unmating force: 1.0 Kgf Min.
  - 2.7 Temperature range: -30°C~80°C
  - 2.8 Waterproof: IPX 7.

# 深圳市精拓金电子有限公司

## 产品图

公称一覽表  
PRODUCT GRANT JMG

公差	单位	制图	制图料号
±0.30 X	MM	YANG	920-16-11-23-21S101L0
±5.°	比例	审核	产品名称
±0.25 X	1:1	郭志富	920-16-11-23-21S101L0
±2.°	SCALE	核准	图法
±0.15 XX	日期	美国荣	版本
±1.°	2019.11.23		A0
±0.10 XXX	DATE		
±0.5°			

G F E D C B A

1 2 3 4 5 6 7 8 9 10